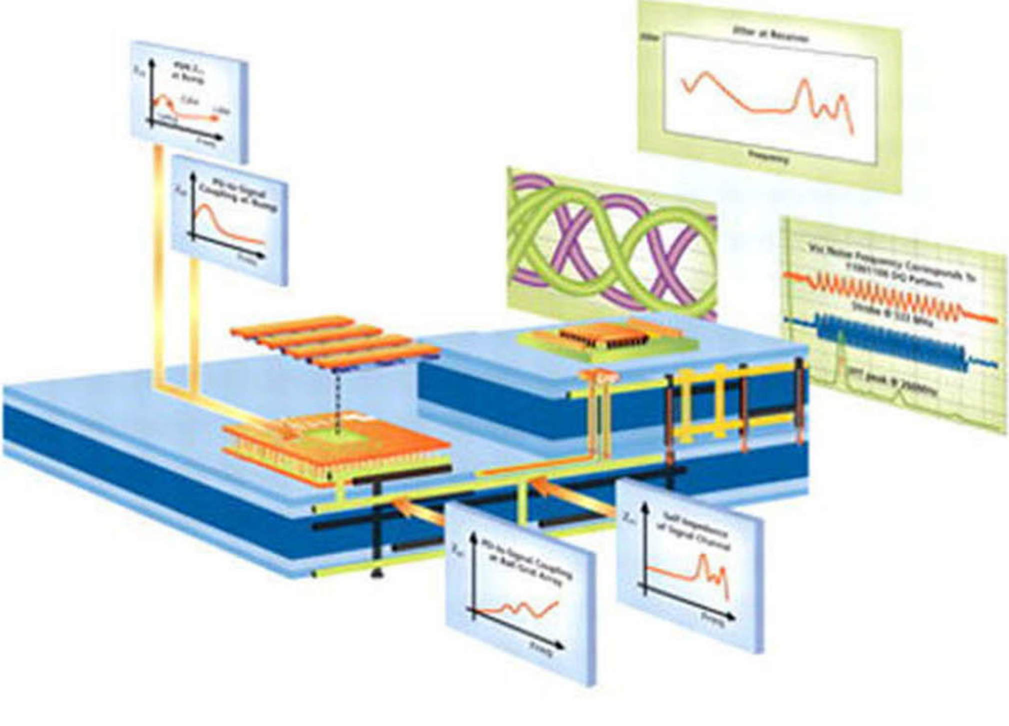
Power Integrity for I/O Interfaces:

With Signal Integrity/Power Integrity Co-Design



Foreword by Joungho Kim

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Modern Semiconductor Design Series

Signal Integrity Library

POWER INTEGRITY FOR I/O INTERFACES

With Signal Integrity/ Power Integrity Co-Design

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